

MATERIAL DECLARATION SHEET



Reliable Electronic Solutions

Material	MF-USMF
Product Line	Multifuse
Revision Date	August 1, 2005
Revision	A
RoHS Compliant	Yes



No.	Breakdown of part (eg Lead, Ceramic body, coating, plating, additive)	Material/substance name (eg.Sn alloy, Cu Copper)	Material/ substance weight in grams (±0.1%)	CAS No. / Int. Identifier	Material /substance weight %	Sum (%)
1	Carbon Black	Carbon	0.0005362	1333-86-4	3.77%	3.77%
2	Copper Plating	Copper	0.0010310		7.24%	7.24%
3	Foil	Copper	0.0068207	7440-50-8	47.90%	50.42%
4	PCB Foil	Nickel	0.0003590	7440-02-0	2.52%	
		Copper	0.0008668	7440-50-8	6.09%	6.09%
5	Polymer	Polyethylene Homopolymer	0.0004751	9002-88-4	3.34%	3.34%
		Proprietary Additives	0.0000006		0.00%	
6	Prepreg	Epoxy	0.0024492		17.20%	28.66%
		Glass Fiber	0.0016326		11.47%	
7	Soldering Plating	Nickel	0.0000678		0.48%	0.48%
		Gold	0.0000008		0.01%	

Total Weight (Grams)	0.0142399	Total	100%	100%
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